

Datasheet: 824261-W11

Etching

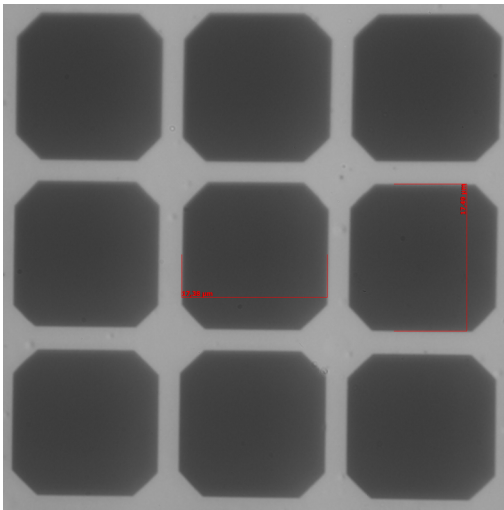
Size:	6 inch
Pitch:	20 μm square
Length:	180 μm
Shape:	straight
Diameter:	9 μm

Postprocessing

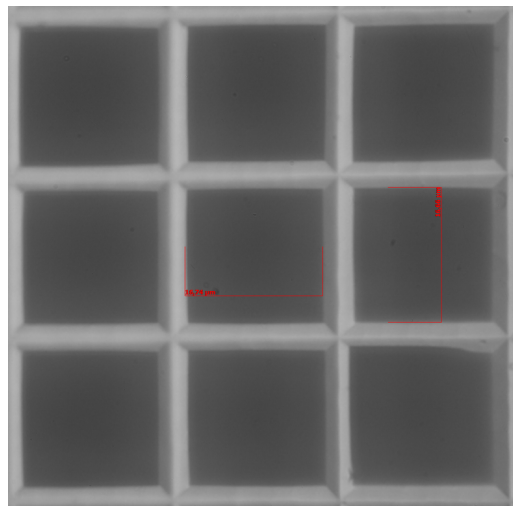
- Substrate removal (membrane thickness approx. 178 μm)
- Anisotropic Pore Widening \rightarrow 17,4 μm
- Measurements

average pore diameter approx. 17.4 μm

Back side view



Front side view



Please note: Most Wafers have a short bottleneck close below the front side. Thus the real porosity of the porous membrane has to be characterized by gravimetric measurements instead of surface microscopy! These images are just as a reference for differences of the surface morphology.